L Number	Hits	Search Text	DB	Time stamp
1	2822	(bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/04/08 17:37
2	27	((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and autocatalytic and immersion and (gold or AU or tin or Sn)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/04/08 16:21
3	0	20010040290.URPN.	USPAT	2004/04/08 16:16
4	2394	((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and (gold or AU or tin or Sn)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/04/08 16:21
5	1010	(((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and (gold or AU or tin or Sn)) and electroless	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/04/08 17:37
6	0	20020033531.URPN.	USPAT	2004/04/08 17:04
7	1010	(((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and (gold or AU or tin or Sn)) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 17:37
8	2825	(bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 17:38
9	3	((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) not ((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 17:38
10	1603	438/613	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 20:08
11	1529	438/613 not (((((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and (gold or AU or tin or Sn)) and electroless)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 20:09
12	0	20020137325.URPN.	USPAT	2004/04/08 18:21
13	0	20010014524.URPN.	USPAT	2004/04/08 18:26
14	0	6649507.URPN.	USPAT	2004/04/08 19:01
15	7	("5496770" | "5633535" | "5665639" | "5882957" | "5904156" | "6051450" | "6218281" | "2001/0028105").PN.	USPAT	2004/04/08 19:01
16	10	6228678.URPN.	USPAT	2004/04/08 19:35
17	3	("5128746" | "5493075" | "6046071").PN.	USPAT	2004/04/08 19:36

18	2319	438/614	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 20:30
19	1794	438/614 not 438/613 not (((((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and (gold or AU or tin or Sn)) and electroless)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 20:30
20	596	(438/614 not 438/613 not (((((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and (gold or AU or tin or Sn)) and electroless)) and (photoresist or resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 20:30
21	2798	438/612	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 20:30
22	1973	438/612 not 438/614 not 438/613 not ((((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and (gold or AU or tin or Sn)) and electroless)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 20:30
23	656	(438/612 not 438/614 not 438/613 not ((((bond or bump) and solder and resist and (pad or land or contact) and (plate or plating) and metal and (through$hole or via or hole)) and (gold or AU or tin or Sn)) and electroless)) and (photoresist or resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 20:30